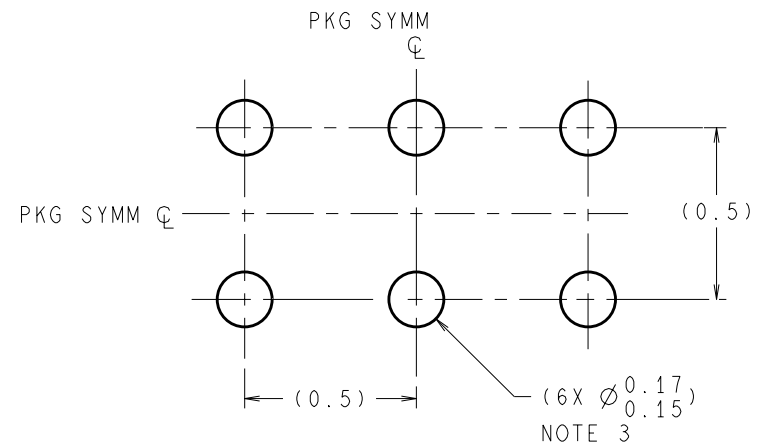
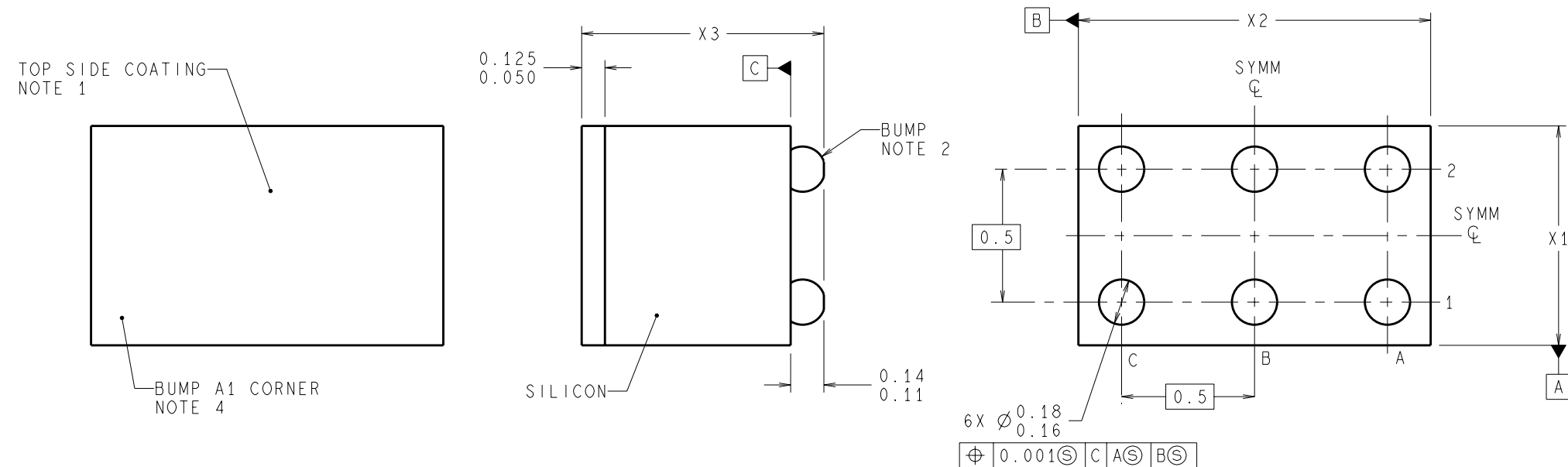


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12285	09/13/1999	MS/NK
B	DIM 0.125/0.05 WAS 0.06/0.04; FLATTEN BUMP HEIGHT BY 0.005mm; X3 TOL 100 WAS 50.	173	10/04/2000	MS/VA
C	CHANGE BUMPS NUMBERING ORDER PER JEDEC; REMOVE DATE FROM NOTE 6; UPDATE NOTE 4.	523	02/11/2002	MS/VP



DIMENSIONS ARE IN MILLIMETERS

LAND PATTERN RECOMMENDATION




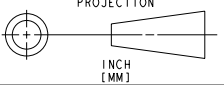
NOTES: UNLESS OTHERWISE SPECIFIED

- EPOXY COATING.
- 63Sn / 37Pb EUTECTIC BUMP.
- RECOMMEND NON-SOLDER MASK DEFINED LANDING PAD.
- PIN A1 IS ESTABLISHED BY LOWER LEFT CORNER WITH RESPECT TO TEXT ORIENTATION.
- XXX IN DRAWING NUMBER REPRESENTS PACKAGE SIZE VARIATION WHERE X1 IS PACKAGE WIDTH, X2 IS PACKAGE LENGTH AND X3 IS PACKAGE HEIGHT (SEE TABLE, SHEET 2).
EXAMPLE: BPA06AFA HAS WIDTH=777, LENGTH=1412, HEIGHT=700
- REFERENCE JEDEC REGISTRATION MO-211, VARIATION BB.

APPROVALS		DATE		 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN MARTA SUCHY		09/13/1999			
DFTG. CHK. THANH LEQUANG		02/11/2002		MICRO SMD, 6 BUMP, 0.5mm PITCH	
ENGR. CHK. VIRAJ PATWARDHAN		02/11/2002			
 PROJECTION INCH [MM]		SCALE N/A	SIZE C	DRAWING NUMBER (SC)MKT-BPA06XXX	REV C
DO NOT SCALE DRAWING				SHEET 1 of 2	

REVISIONS			
LTR	DESCRIPTION	E.C.N.	DATE
	SEE SHEET 1		

PACKAGE DIMENSIONS					
X1 DESIGNATOR	X1 PACKAGE WIDTH $\pm 30\mu\text{m}$	X2 DESIGNATOR	X2 PACKAGE LENGTH $\pm 30\mu\text{m}$	X3 DESIGNATOR	X3 PACKAGE HEIGHT $\pm 100\mu\text{m}$
A	777	A	1285	A	700
B	803	B	1311	B	850
C	828	C	1336	C	900
D	853	D	1361		
E	879	E	1387		
F	904	F	1412		
G	930	G	1438		
H	955	H	1463		
J	980	J	1488		
K	1006	K	1514		
L	1031	L	1539		
M	1057	M	1565		
N	1082	N	1590		
P	1107	P	1615		
Q	1133	Q	1641		
R	1158	R	1666		
S	1184	S	1692		
T	1209	T	1717		
U	1234	U	1742		
V	1260	V	1768		
W	1285	W	1793		
X	1311	X	1819		
Y	1336	Y	1844		
2	1361	2	1869		
3	1387	3	1895		
4	1412	4	1920		
5	1438	5	1946		
6	1463	6	1971		

APPROVALS	DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DRAWN MARTA SUCHY	09/13/1999			
DFTG. CHK. THANH LEQUANG	02/11/2002			
ENGR. CHK. VIRAJ PATWARDHAN	02/11/2002			
		MICRO SMD, 6 BUMP, 0.5mm PITCH		
		SCALE N/A	SIZE C	DRAWING NUMBER (SC)MKT-BPA06XXX
DO NOT SCALE DRAWING		SHEET 2 of 2		